Actively Cooled Silicon Lightweight Mirrors for Far Infrared and Submillimeter Optical Systems Phase II SBIR Contract No, NNM05AA16C John West and Dr. Phil Stahl NASA MSFC



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Briefing Outline

- Background
- Why SLMS[™] for Cryogenic Optics
- Phase II Project



- Achieving a telescope temperature of 4 Kelvin is one of the key technology development demonstrations that must occur in order to unravel the secrets of the early universe
- ~50% of the luminosity of the universe and 98% of the photons (excluding the cosmic microwave background) occur in the FIR
 - \Rightarrow That is where the young universe is redshifted
- Development of technology for 10-25 meter diameter optics for 20-800 μ m bandwidth, with an areal density <5 kg/m², and a surface figure specification of λ /14 at 20 μ m required for future FIR/SMM missions
 - \Rightarrow Premium for wavelengths >100 μ m to achieve mirror temperatures lower than 10 K
 - \Rightarrow Some missions such as TPF-C require extreme figure and finish performance
- TRL 6 must be demonstrated for Cryogenic Optics and Telescopes
- SLMS[™] technology development and demonstration effort is directly aligned with the vision of the FIR/SMM community

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Why SLMS[™] for Cryogenic Optics (1 of 2)

- Lightweight Optical Systems (LWOS) Superior Technology with a System Level Point-of-View®
 - Super-polishable, low distortion, dimensionally stable silicon skin:
 - \Rightarrow Avg CTE from 20-310K = 0.95 ± 0.01 ppm/K, 0.25 ppm/K instantaneous @ 20K
 - \Rightarrow High thermal conductivity: >5000 W/m-K at 25 K
 - Silicon foam core is open-celled (up to 95% void space)
 - \Rightarrow Same CTE as skin, thermal conductivity ~50 W/m-K
 - ⇒ 1^{st} fundamental frequency (120.35 ± 0.175 Hz) and damping (0.0055% ± 0.0043%) are temperature insensitive from 20-300K (20x2x0.5 inch bar measured by JPL values are geometry dependent)
 - Static and Transient Distortion parameters are incredibly small!
 - SLMS[™] engineered construct provides areal density and 1st fundamental frequency that match or exceeds lightweighted beryllium
 - High-stiffness reduces risk for phase matching segments
 - SLMS[™] is super-polishable like glass or glass-ceramics
 - Exceptional figure and finish values have been demonstrated



Why SLMS[™] for Cryogenic Optics (2 of 2)

- SLMS[™] can be cooled either Internally or Externally
- Phase I demonstrated Very Rapid and Uniform cooling for both Internal and External cooling modes with LN2
- Uniform external cooling of skin using Joule-Thompson cooler, or manifold, or cold plate, etc.
- In situ heat exchanger for Internal Cooling
 - ⇒ Uniform active cooling by flowing a coolant fluid (e.g. LHe) directly through foam core of mirror
 - \Rightarrow Foam structure has large surface area, and low flow resistance
 - \Rightarrow 1 ft³ of foam has 1500-2000 ft² of heat transfer surface area
- Prior testing at NASA MSFC demonstrated minimal print-through (3.7 nm RMS) and figure change (λ /100 RMS HeNe) for 300 K to 24 K temperature change (radiative)

SLMS[™] Transient Distortion Parameter is Orders of Magnitude **Better Than Any Other Material** No Cryo-Nulling is Required, No Actuators for Figure Control High Stiffness Should Minimize Phase Matching Issues

- Matures Cryogenic Optic Technology to TRL6 at Component Level
 In Line With NASA Technology Development/Demonstration Goals
- Provides Useable Primary Mirror for Future NASA Mission
- Phase II Project Tests 55 cm Diameter SLMS[™] Mirror at 4K using External Active Cooling
 - ⇒ Far Infrared Submillimeter Prototype (FISP) Mirror (Deliverable)
 - \rightarrow FISP SLMSTM substrate being diamond turned by Corning NetOptix (CNO)
 - \Rightarrow Manifold/Mount for Cooling to 4 K (Deliverable)
 - \rightarrow CeSic[®] manifold/mount has been manufactured





Lightweight Optical Systems (LWOS)

Superior Technology with a System Level Point-of-View®

FISP SLMS[™] PM Requirements

- Far Infrared Submillimeter Prototype (FISP) Mirror Suitable for Cryogenic Testing at NASA/MSFC
 - \Rightarrow Optical Surface
 - → CA: 50-cm; ROC: 1500 mm; Kappa: -1.0 (parabolic)
 - \rightarrow Figure: 2 waves rms at 633 nm
 - \rightarrow Roughness: 10 nm rms
 - \rightarrow Scratch/Dig: 80/50
 - \Rightarrow Mechanical
 - \rightarrow Overall Dia.: 55 cm
 - \rightarrow Overall thick.: 4.1 cm
 - \rightarrow Front annulus: 0.7 cm
 - → Flat Back Surface Flatness: 0.025 mm
 - ⇒ Material Properties
 - → 1.0 mm Silicon Skin Thickness
 - \rightarrow **10-12% Silicon foam**
 - ⇒ Predicted Mass Properties
 - \rightarrow Mass = 2.77 kg
 - \rightarrow Areal density = 11.7 kg/m²



FISP SLMS™ PM Construction

• Foam Core Optics with a Continuous Shell



Polycrystalline Silicon 100% Dense Skin 0.25-1.4 mm typical thickness

- Foam is Open-Cell, 90% Porosity
- Pore Size: 0.40 per mm (100 per in)
- 1500-2000 ft² surface area/ft³
- CNC machined to parabolic shape to ± 50 µm (0.002 inch)



Parabolic Shape Machined Into Foam Core

hafer Lightweight Optical Systems (LWOS)

NASA Diamond Turning Poly-silicon Superior Technology with a System Level Point-of-View®

- Dr. David Lehner and Mr. Arthur Lapietra of NASA/MSFC developed a process for single • point diamond turning (SPDT) of poly-silicon in 2006 under NASA IRAD
 - Previous attempts to SPDT poly-silicon by diamond turning vendors were based on • SPDT of single crystal silicon (aqueous cutting fluids, expensive natural diamond tools, and a -30° rake angle) and resulted in poor finishes and damaged surfaces from rapid tool wear
 - NASA/MSFC key innovations were using a non-aqueous cutting fluid, a cheap ٠ polycrystalline diamond (PCD) tool for near-net shaping, light finish cuts using a natural diamond tool, and a 0° rake angle







Precitech Optimum 4200 SPDT Lathe

PCD Tool Roughing

Natural Diamond Tool Finish

CNO incorporating MSFC Innovations To Diamond Turn FISP SLMS[™] PM



Lightweight Optical Systems (LWOS)

Superior Technology with a System Level Point-of-View®

Assembly for Cryogenic Testing



• Bonding agent

⇒Approximately .002-in thick bond line continuous over back surface of mirror

- Manifold
 - \Rightarrow CeSic[®] upper and lower halves
 - \rightarrow Upper half routes cooling agent near mirror
 - \rightarrow Lower half routes cooling agent to and from test stand

- Cesic[®] manifold/mount has been manufactured
- Diamond turning of the first large parabolic SLMS[™] substrate underway
- Successful transition of government sponsored research into industry use